

IN THE CLAIMS

Please amend the claims as follows. Presented below is a complete listing of claims in the revised format showing markings as set forth by the U.S. Patent and Trademark Office on January 31, 2003:

1-12. (Canceled).

13. (Currently Amended) An packaged inductor comprising:

a substrate;

a first insulating layer over the substrate;

posts over the insulating layer;

a conductive layer deposited on top of the posts and in a pattern on the substrate, the conductive layer on the tops of the posts for coupling the packaged inductor to another device.

14. (Currently Amended) The packaged inductor of claim 13, further comprising:

a protective layer over the conductive layer, the posts, and the first insulating layer, ~~the second insulating~~ protective layer leaving exposed the conductive layer on the top of the posts.

15. (Original) The packaged inductor of claim 13, wherein the first insulating layer is a polyimide layer which provides compliancy to the packaged inductor.

16. (Currently Amended) The packaged inductor of claim 13, wherein the posts are made of one or more of the materials including: silicon, gallium arsenide,

silicon germanium, silicon carbide, gallium phosphide, ceramic materials, sapphire, quartz, and other substrate materials.

17. (Original) The packaged inductor of claim 13, wherein the conductive layer is gold.

18. (Currently Amended) The packaged inductor of claim 14, wherein the ~~second insulating~~ protective layer is of polyimide which provides compliancy to the packaged inductor.

19. (Currently Amended) The packaged inductor of claim 18 ~~16~~, wherein the protective layer comprises a first layer of nickel and a second layer of flash gold.

20-40. (Canceled)

41. (New) A packaged inductor comprising:
a substrate including a plurality of posts having a top;
conductive layer a pattern on the substrate to form an inductor, the conductive layer extending to the top of the posts;
the top of the posts used for coupling the packaged inductor to another device.

42. (New) The packaged inductor of claim 41, further comprising:
a first insulating layer over the conductive layer.

43. (New) The packaged inductor of claim 42, wherein the first insulating layer comprises a compliant material, the compliant material providing compliancy to the packaged inductor.

44. (New) The packaged inductor of claim 43, wherein the first insulating layer is a polyimide layer.

45. (New) The packaged inductor of claim 41, further comprising:
a protective layer over the conductive layer, the posts, and the first insulating layer.

46. (New) The packaged inductor of claim 45, wherein the protective layer is a polyimide to provide compliancy to the packaged inductor.

47. (New) The packaged inductor of claim 45, wherein the protective layer comprises a first layer of nickel, and a second layer of gold.

48. (New) The packaged inductor of claim 41, wherein the posts are made of one or more of the materials including: silicon, gallium arsenide, silicon germanium, silicon carbide, gallium phosphide, ceramic materials, sapphire, quartz, and other substrate materials.

49. (New) The packaged inductor of claim 41, wherein the conductive layer is gold.

50. (New) The packaged inductor of claim 41, wherein the pattern of the inductive layer is in a spiral pattern.

51. (New) The packaged inductor of claim 50, wherein the plurality of posts comprise a first post and a second post, the first post located at an inside end of the spiral pattern, and the second post located at an outside end of the spiral pattern.

52. (New) The packaged inductor of claim 41, further comprising:
a contact layer on the conductive layer on top of the posts, the contact layer designed to be directly in contact with a printer circuit board.

53. (New) A packaged inductor comprising:
a substrate;
a passivation layer over the substrate;
an insulating layer over the passivation layer;
inside post and an outside post over the insulating layer;
a conductive layer over the top of the posts, the conductive layer deposited as a spiral pattern between the inside post and the outside post;
a fixing passivation layer to isolate the conductive layer, the fixing passivation layer leave a tops of the inside post and the outside post exposed; and
a contact layer on the conductive layer on the tops of the inside post and the outside post to protect the conductive layer, the contact layer designed to be placed in contact with a printed circuit board.